

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10769047			
<b>Filing Date:</b>	30-Jan-2004			
<b>Title of Invention:</b>	LOW-TEMPERATURE, LOW-RESISTIVITY HEAVILY DOPED P-TYPE POLYSILICON DEPOSITION			
<b>First Named Inventor/Applicant Name:</b>	S. Brad Herner			
<b>Filer:</b>	Leon Radomsky/Michelle Richardson			
<b>Attorney Docket Number:</b>	035905-0164 MA-100-I			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appt Issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1740